



Features

- 1 Molex "Mirror Mezz" Licensed Second Source
- 2 High Speed Transmission (56+Gbps NRZ / 112+Gbps PAM4)
- 3 OAM Specified Connector (688pos.)
- 4 High Pin Count, High Density: 404pos. (101 Differential Pairs), 688pos. (172 Differential Pairs)
- 5 Hermaphroditic Connector
- 6 Stub-less 2-point Contact Design
- 7 Protective Housing that Encapsulates the Contact Tips Prevents Warping During Mating



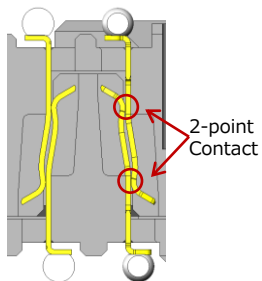
High-Speed

Low Profile

Stacking

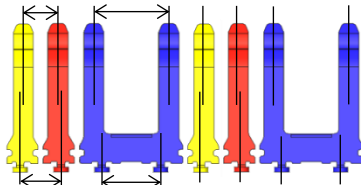
Contact Design

Stub-less Design



- Superior SI Performance
- 2-point Contact for Enhanced Reliability
- Wiping Amount: 1.5mm Max.

Impedance Matching (92Ω Target)

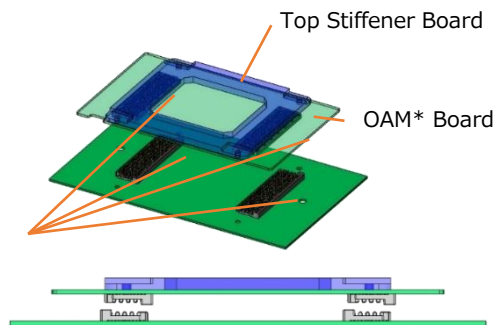


Pitch differs from contact portion and mounted portion for impedance optimization.

Used in OAM* (OCP Accelerator Module)



IT14:
5mm Stacking Height (2.5mm + 2.5mm)
688pos.
172 Differential Pairs



*OAM=OCP (Open Computer Project) Accelerator Module

Specifications

Rated Current	1.2A
Rated Voltage	30V AC/DC
Operating Temperature	-55 to +105°C
Contact Resistance*	30mΩ Max.
Withstanding Voltage	500V AC for 1 min.
Insulation Resistance	1,000MΩ Min. (500V DC)
Mating Durability	100 times

*Includes conductor resistance.

-No. of Pos.: 404pos. (with/without Peg), 688pos. (with Peg)

Molex Part No. Compatibility List

HRS Part No.	HRS No.	Molex Part No.
IT14-404S-BGA-2.5H	CL0636-6005-0-00	202828-1506
IT14A-404S-BGA-2.5H	CL0636-6006-0-00	202828-0029
IT14-688S-BGA-2.5H	CL0636-6001-0-00	209311-1115

Product Number Structure

IT14# - ###S - BGA - 2.5H (##)

1 2 3 4 5

1 Series Name	IT14: With Peg IT14A: Without Peg
2 No. of Pos.	404, 688
3 Design	BGA
4 Height	2.5H: 2.5mm (Stacking Height: 5.0mm)
5 Specifications	(11): No adhesive tape (15): Vacuum packaging